

L Number	Hits	Search Text	DB	Time stamp
1	541619	nickel ni	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 17:36
2	3993	buffer with (nickel ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 17:36
3	13274809	"5" "6" "7" "8" "9" "10" with (buffer with (nickel ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 17:37
4	2518	("5" "6" "7" "8" "9" "10") with (buffer with (nickel ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:29
5	2026	(micro micrometer mm nm) with (("5" "6" "7" "8" "9" "10") with (buffer with (nickel ni)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 17:44
6	3	(chip semiconductor die ic (integrated adj circuit) dice) same ((micro micrometer mm nm) with (("5" "6" "7" "8" "9" "10") with (buffer with (nickel ni))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 17:45
7	2086	(thickness measurement thick micro micrometer mm nm) with (("5" "6" "7" "8" "9" "10") with (buffer with (nickel ni)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:30
8	13	(chip semiconductor die ic (integrated adj circuit) dice) same ((thickness measurement thick micro micrometer mm nm) with (("5" "6" "7" "8" "9" "10") with (buffer with (nickel ni))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:31
9	1		USPAT	2004/01/18 18:14
10	141350	("5" "6" "7" "8" "9" "10") with (nickel ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:29
11	53830	(thickness measurement thick micro micrometer mm nm) with (nickel ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:30
12	3954	(chip semiconductor die ic (integrated adj circuit) dice) same ((thickness measurement thick micro micrometer mm nm) with (nickel ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:31
13	74	((chip semiconductor die ic (integrated adj circuit) dice) same ((thickness measurement thick micro micrometer mm nm) with (nickel ni))) same buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/18 18:31